

Notice of References Cited	Application/Control No. 10/802,653		Applicant(s)/Patent Under Reexamination EISENSCHMID ET AL.	
	Examiner David A. Rogers		Art Unit 2856	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-4,241,384	12-1980	Diziere, Bernard	362/203
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

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	N					
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	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	"Molded Interconnect Devices Reshape Electromechanical Design", September 2000, available on the Internet at < http://www.elecdesign.com >.
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.